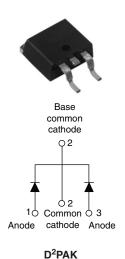


Vishay High Power Products

HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A



PRODUCT SUMMARY				
V_R	600 V			
V _F at 15 A at 25 °C	1.7 V			
I _{F(AV)}	2 x 15 A			
t _{rr} (typical)	19 ns			
T _J (maximum)	150 °C			
Q _{rr} (typical)	80 nC			
dI _{(rec)M} /dt (typical) at 125 °C	160 A/μs			
I _{RRM} (typical)	4.0 A			

FEATURES

- Ultrafast recovery
- · Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- · Specified at operating conditions
- Designed and qualified for industrial level

BENEFITS

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- · Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION

HFA30TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the HFA30TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RBM}) and does not exhibit any tendency to "snap-off" during the t_h portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA30TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V_{R}		600	V	
Maximum continuous forward current per leg	l _F	T _C = 100 °C	15		
per device			30	Α	
Single pulse forward current	I _{FSM}		150	^	
Maximum repetitive forward current	I _{FRM}		60		
Maximum power dissipation	P _D	T _C = 25 °C	74	°C	
Maximum power dissipation		T _C = 100 °C	29]	
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	W	

HFA30TA60CS

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ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		600	-	-	
		I _F = 15 A	See fig. 1	-	1.3	1.7	V
Maximum forward voltage	V_{FM}	I _F = 30 A		-	1.5	2.0	
		I _F = 15 A, T _J = 125 °C		-	1.2	1.6	
Maximum reverse		$V_R = V_R$ rated	Coo fig. 0	-	1.0	10	
leakage current	I _{RM}	$T_J = 125 ^{\circ}\text{C}, V_R = 0.8 \text{x} V_R \text{rated}$	See fig. 2	-	400	1000	μΑ
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	25	50	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		=	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		-	19	-	
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C		-	42	60	ns
occ lig. 5, 10	t _{rr2}	T _J = 125 °C		-	70	90	
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	4.0	6.0	Α
See fig. 6	I _{RRM2} T _J = 125 °C I _F = 15 A	I _F = 15 A	-	6.5	10	^	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C	$dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	80	180	nC
See fig. 7	Q _{rr2}	T _J = 125 °C		-	220	450	110
Peak rate of fall of recovery current during t _b See fig. 8	dI _{(rec)M} /dt1	T _J = 25 °C		-	188	-	- A/μs
	dI _{(rec)M} /dt2	T _J = 125 °C		-	160	-	Ανμδ

THERMAL - MECHANICAL SPECIFICATIONS PER LEG						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Junction to case, single leg conducting	B		-	-	1.7	
Junction to case, both legs conducting	R _{thJC}		-	-	0.85	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
vveignt			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D ² PAK		HFA30TA60CS		



HEXFRED® Vishay High Power Products Ultrafast Soft Recovery Diode, 2 x 15 A

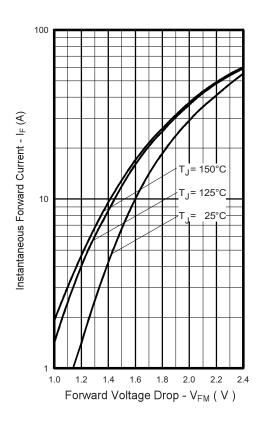


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

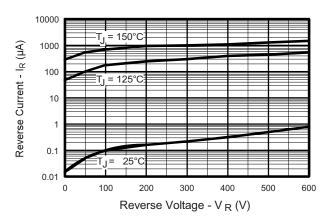


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

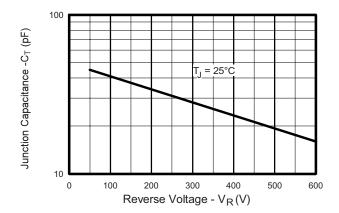


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

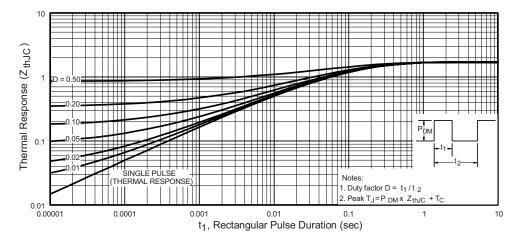


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

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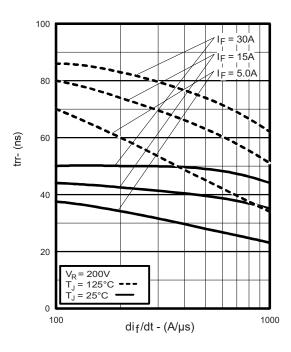


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

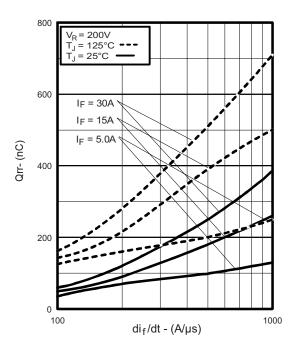


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

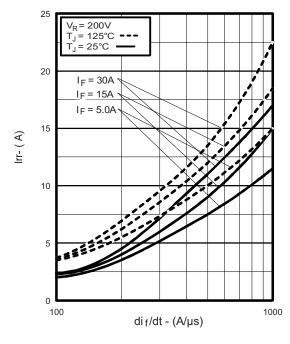


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

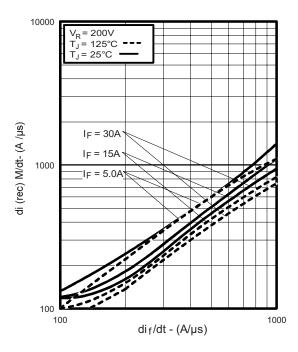


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)



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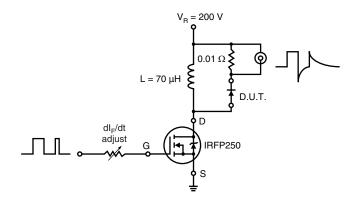
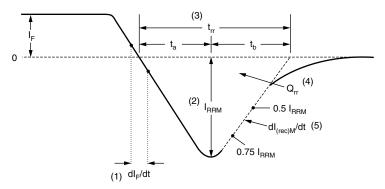


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

LINKS TO RELATED DOCUMENTS				
Dimensions http://www.vishay.com/doc?95046				
Part marking information	http://www.vishay.com/doc?95054			
Packaging information	http://www.vishay.com/doc?95032			



Vishay

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